

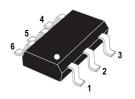
SSCSBAV99SG

Fast Switching Diode

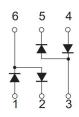
Features

- ♦ Fast Switching Speed
- ♦ Ultra-Small Surface Mount Package
- ♦ Low Reverse Leakage Current
- ♦ Ideal for Battery Powered Portable Applications
- ♦ RoHS Compliant/Green EMC
- ♦ Moisture Sensitivity: Level 3 per J-STD-020

PIN configuration



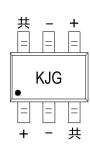
SOT-363



Applications

- ♦ High-speed switching for detection
- ♦ Battery Powered Portable
- ♦ Mobile phones, laptops and other electronic devices

Circuit Diagram



Marking

Absolute maximum rating (T_A=25^oC unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Repetitive Peak Reverse Voltage	V_{RRM}		
Working Peak Reverse Voltage	V _{RWM}	75	V
DC Blocking Voltage	V _R		
Average Rectified Output Current	Io	150	mA
Forward Continuous Current	I _{FM}	300	mA
Non-repetitive Peak Forward Surge Current @ t=8.3ms	I _{FSM}	2.0	Α
Power Dissipation	P _D	200	mW
Thermal Resistance from Junction to Ambient	R _{eJA}	625	°C/W
Junction Temperature	TJ	125	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

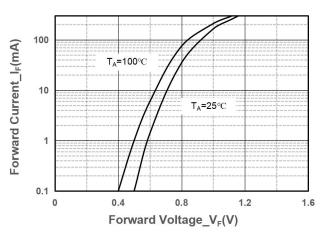


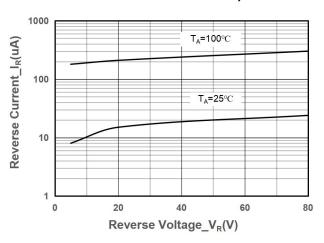


• Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Reverse Voltage	V_R	I _R = 2.5uA	75			V
Forward Voltage	V _F	I _F =1mA			0.715	V
		I _F = 10mA			0.855	V
		I⊧ = 50mA			1	V
		I _F = 150mA			1.25	V
Reverse Current	I _R	V _R = 25V			25	nA
		V _R = 75V			2.5	μA
Junction Capacitance	CJ	V _R = 0V, f = 1MHz			2	pF
Reverse recovery time	t _{rr}	I _F =I _R =10mA, R _L =100Ω, I _{rr} =0.1I _R			4	ns

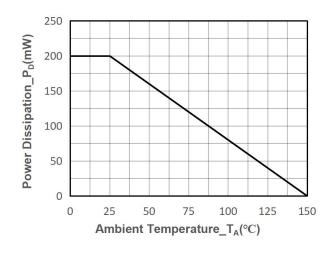
• Typical Performance Characteristics (T_A=25℃ unless otherwise noted)

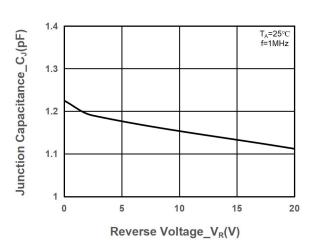




Forward Current vs. Forward Voltage

Reverse Current vs. Reverse Voltage





Power Derating vs. Ambient Temperature

Junction Capacitance vs. Reverse Voltage



• Package Information

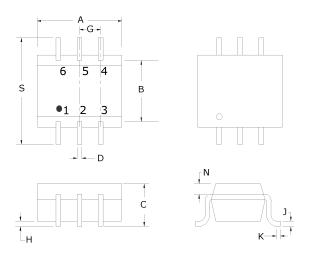
Ordering Information

Device	Package	Marking	Qty per Reel	Reel Size
SSCSBAV99SG	SOT-363	KJG	3000	7 Inch

Mechanical Data

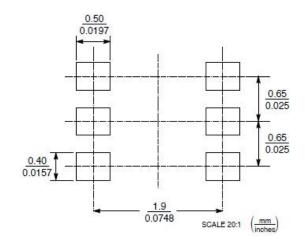
Case: SOT-363

Case Material: Molded Plastic. UL Flammability



DIM	Millimeters			
DIM	Min	Nom	Max	
Α	1.90	2.00	2.20	
В	1.15	-	1.35	
С	0.90	-	1.10	
D	0.15	-	0.35	
G	0.65BSC			
Н	-	-	0.10	
J	0.08	-	0.15	
K	0.15	-	0.35	
S	2.10	-	2.45	
N	0.20REF			

Recommended Pad outline





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